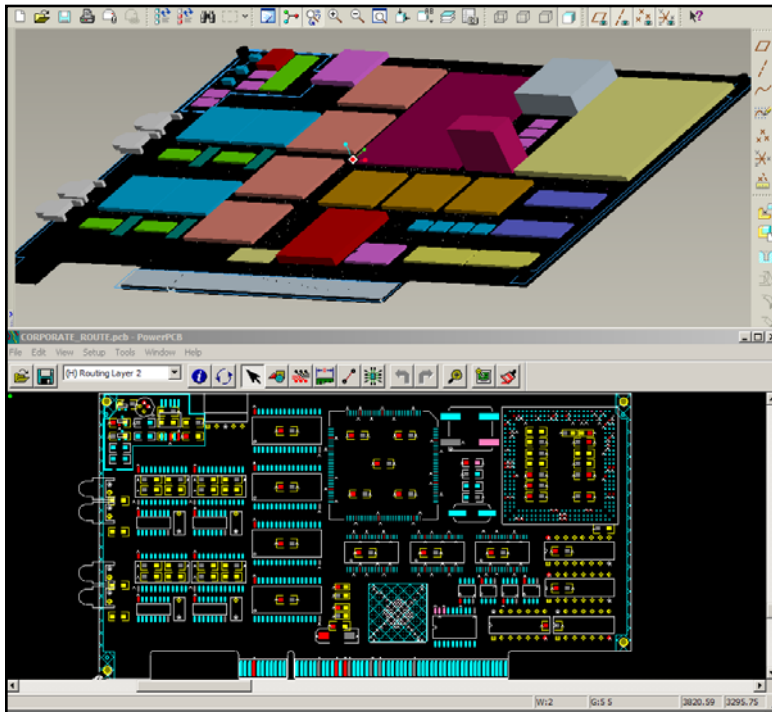


IDF Link



With IDF Link, you can connect your PADS Layout system to CAD/CAM solutions such as Pro/ENGINEER®.

Overview

By adding IDF Link to your seat of PADS® Layout, you can investigate how a placed printed circuit board will be modeled as a subassembly in a larger, or final-product, solids model. Once the PCB is modeled in the 3D mechanical design software, you can investigate mass/material properties of the printed circuit board subassembly and use other applications specific for solids modeling.

Bi-Directional Data Exchange

IDF Link is fully integrated with PADS Layout for efficient bi-directional data exchange of 2D printed circuit board information. Data transferred include board outline and thickness, mounting holes, keep-out areas, components, and placement information. Component height (Z dimension) values are determined in PADS Layout and automatically passed to 3D mechanical tools thus eliminating the requirement to develop 3D libraries in Pro/ENGINEER and other 3D mechanical software solutions.

Major product features:

- Avoids assembly violations by creating PCB models upfront
- Simulates the impact of component placement and final packaging decisions
- Fully exchanges data bi-directionally with PADS Layout
- Back annotates to ensure continuous data integrity
- Automatically determines and passes values to Pro/ENGINEER and other 3D mechanical tools

Move Components in PADS Layout

You can use your 3D mechanical design tool to move components placed in PADS Layout so that any physical interference or violations are avoided in assembly. Component information, mounting-hole repositioning, keep-out area modification, and board outline are all back annotated to PADS Layout to ensure consistency and data integrity.

Link to Your Overall Design Process

Implement IDF Link in your overall design process to simulate the impact of component placement and final packaging decisions early in the design cycle. The strong integration of the electronic and mechanical applications provided by the link ensures high product quality and shortened time-to-market schedules.

Note: You must have the ECAD option on your Pro/ENGINEER system for the IDF Link to work. The ECAD option is available from PTC (Parametric Technology Corporation).

PADS-PowerPCB Options

- Advanced Packaging Toolkit
- Advanced Rule Set (ARS)
- Assembly Variants
- Chip-on-Board Toolkit
- DFT Audit
- IDF Link
- PADS AutoRouter
- PADS Router
- Physical Design Reuse (PDR)

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Corporate Headquarters
Mentor Graphics Corporation
8005 SW Boeckman Road
Wilsonville, OR 97070-7777
Phone: 503.685.7000
Fax: 503.685.1204

Systems Design Division
Mentor Graphics Corporation
1811 Pike Road
Longmont, CO 80501
Phone: 720.494.1000
Sales: 888.482.3322
Email: pads_info@mentor.com

